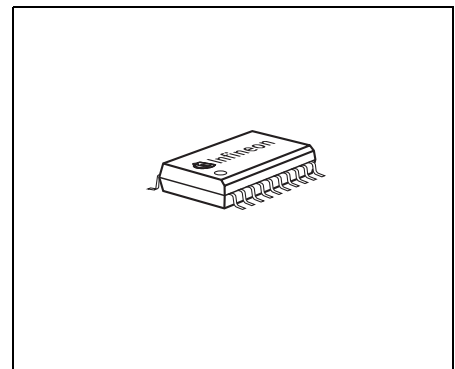
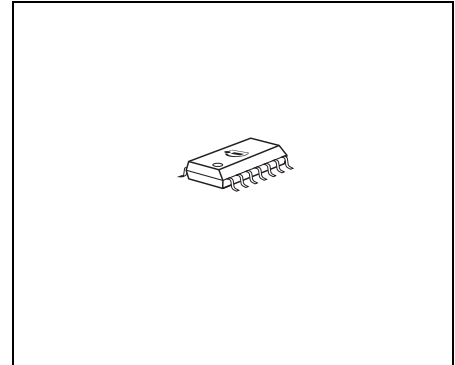




Features

- Output voltage tolerance $\leq \pm 2\%$
- 200 mA output capability
- Low-drop voltage
- Very low standby current consumption
- Overtemperature protection
- Reverse polarity protection
- Short-circuit proof
- Adjustable reset threshold
- Wide temperature range
- Suitable for use in automotive electronics
- Green Product (RoHS compliant)
- AEC Qualified



Functional Description

TLE 4262 GM is a 5-V low-drop voltage regulator in a PG-DSO-14 or PG-DSO-20 SMD package. The maximum input voltage is 45 V. The maximum output current is more than 200 mA. The IC is short-circuit proof and includes a temperature protection which turns off the IC at overtemperature.

The IC regulates an input voltage V_I in the range of $6\text{ V} < V_I < 45\text{ V}$ to $V_{Q,nom} = 5.0\text{ V}$. A reset signal is generated for an output voltage of $V_{Q,rt} < 4.5\text{ V}$. This voltage threshold can be decreased to 3.5 V by external connection of a voltage divider. The reset delay can be set externally with a capacitor. The IC can be switched off via the inhibit input, which reduces the current consumption from 900 μA to typical 0 μA .

Type	Package
TLE 4262 GM	PG-DSO-14-30
TLE 4262 G	PG-DSO-20-35

Dimensioning Information on External Components

The input capacitor C_1 is necessary for compensation of line influences. Using a resistor of approx. $1\ \Omega$ in series with C_1 , the oscillating circuit consisting of input inductivity and input capacitance can be damped. The output capacitor is necessary for the stability of the regulating circuit. Stability is guaranteed at values $\geq 22\ \mu\text{F}$ and an ESR of $\leq 3\ \Omega$ within the operating temperature range. For small tolerances of the reset delay, the spread of the capacitance of the delay capacitor and its temperature coefficient should be noted.

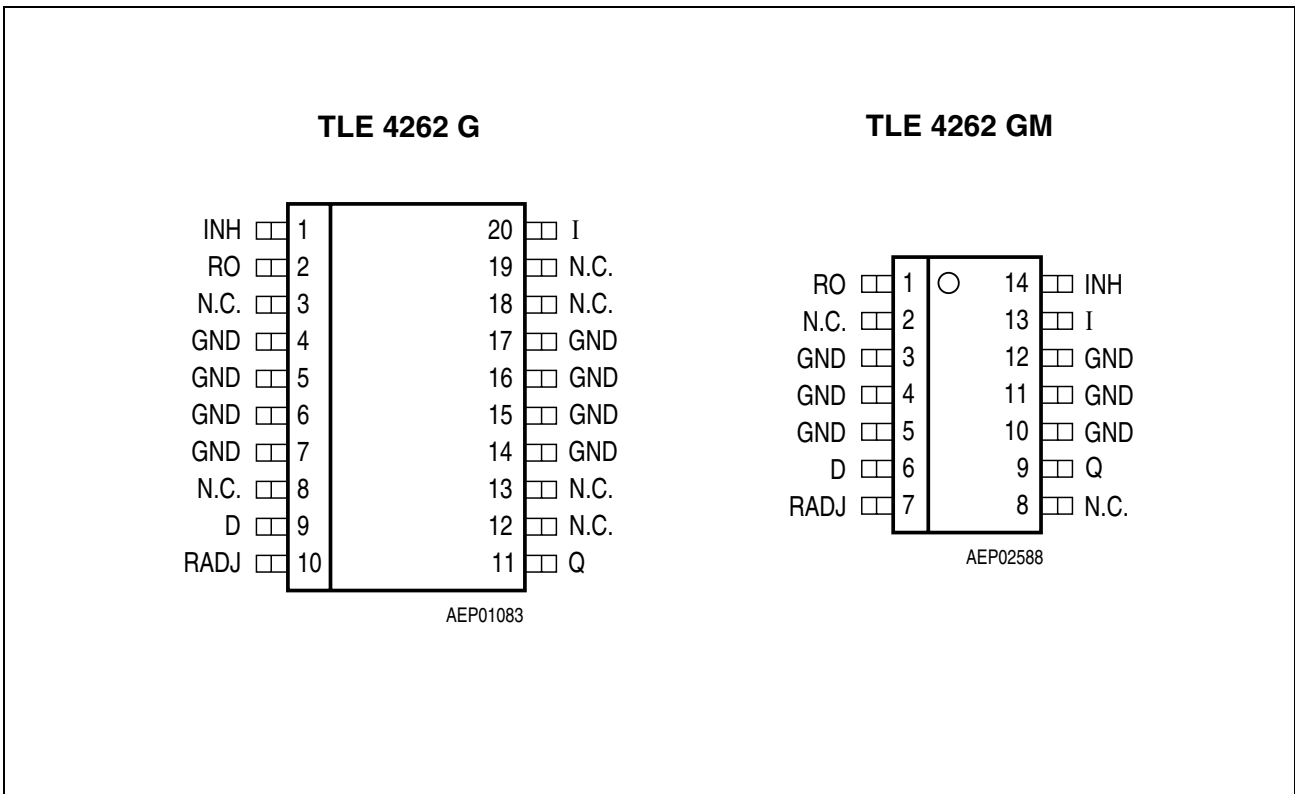


Figure 1 Pin Configuration (top view)

Table 1 Pin Definitions and Functions

Pin PG-DSO-14- 30	Pin PG-DSO-20- 35	Symbol	Function
1	2	RO	Reset output; open-collector output internally connected to the output via a resistor of 30 kΩ.
2, 8	3, 8, 12, 13, 18, 19	N.C.	Not connected
3 - 5, 10 - 12	4 - 7, 14 - 17	GND	Ground
6	9	D	Reset delay; connect capacitor to GND for setting delay time
7	10	RADJ	Reset threshold; for setting the switching threshold connect by a voltage divider from output to ground. If this input is connected to GND, reset is triggered at an output voltage of 4.5 V.
9	11	Q	5-V output voltage; block to ground by capacitor with $C \geq 22 \mu\text{F}$, $\text{ESR} \leq 3 \Omega$ at 10 kHz.
13	20	I	Input voltage; block to ground directly at the IC by a ceramic capacitor.
14	1	INH	Inhibit; TTL-compatible, low-active input

Table 2 Absolute Maximum Ratings

Parameter	Symbol	Limit Values		Unit	Remarks
		Min.	Max.		
Input I					
Input voltage	V_I	-42	45	V	–
Input current	I_I	–	–	–	internally limited
Reset Output RO					
Voltage	V_{RO}	-0.3	42	V	–
Current	I_{RO}	–	–	–	internally limited
Reset Input RADJ					
Voltage	V_{RADJ}	-0.3	6	V	–
Reset Delay D					
Voltage	V_D	-0.3	42	V	–
Current	I_D	–	–	–	internally limited
Output Q					
Voltage	V_Q	-5.25	V_I	V	–
Current	I_Q	–	–	–	internally limited
Inhibit INH					
Voltage	V_{INH}	-42	45	V	–
Ground GND					
Current	I_{GND}	-0.5	–	A	–
Temperature					
Junction temperature	T_j	–	150	°C	–
Storage temperature	T_{stg}	-50	150	°C	–
Operating Range					
Input voltage	V_I	5.2	45	V	1)
Junction temperature	T_j	-40	150	°C	–
Thermal resistance junction-ambient	R_{thj-a}	–	112	K/W	2)
junction-case	R_{thj-p}	–	32	K/W	3)

1) Corresponds with characteristics of drop voltage, output current and power description (see diagrams).

2) Package mounted on PCB 80 × 80 × 1.5 mm³; 35μ Cu; 5μ Sn; Footprint only; zero airflow.

3) Measured to pin 4.

Table 3 Characteristics
 $V_I = 13.5\text{ V}; T_j = 25\text{ }^\circ\text{C}; V_{\text{INH}} > 3.5\text{ V};$ (unless specified otherwise)

Parameter	Symbol	Limit Values			Unit	Test Condition
		Min.	Typ.	Max.		
Normal Operation						
Output voltage	V_Q	4.90	5.00	5.10	V	$5\text{ mA} \leq I_Q \leq 150\text{ mA};$ $6\text{ V} \leq V_I \leq 28\text{ V};$ $-40\text{ }^\circ\text{C} \leq T_j \leq 125\text{ }^\circ\text{C}$
Output voltage	V_Q	4.90	5.00	5.10	V	$6\text{ V} \leq V_I \leq 32\text{ V};$ $I_Q = 100\text{ mA}$ $T_j = 100\text{ }^\circ\text{C}$
Output current limiting	I_Q	200	250	–	mA	–
Current consumption; $I_q = I_i - I_Q$	I_q	–	0	50	μA	$V_{\text{INH}} = 0\text{ V}$
	I_q	–	0.9	1.3	mA	$I_Q = 0\text{ mA}$
	I_q	–	10	18	mA	$I_Q = 150\text{ mA}$
	I_q	–	15	23	mA	$I_Q = 150\text{ mA}; V_i = 4.5\text{ V}$
Drop voltage	V_{DR}	–	0.35	0.50	V	$I_Q = 150\text{ mA}^1)$
Load regulation	$\Delta V_{Q,\text{lo}}$	–	–	25	mV	$I_Q = 5\text{ mA to } 150\text{ mA}$
Line regulation	$\Delta V_{Q,\text{li}}$	–	3	25	mV	$V_I = 6\text{ V to } 28\text{ V};$ $I_Q = 150\text{ mA}$
Power Supply Ripple Rejection	$PSRR$	–	54	–	dB	$f_r = 100\text{ Hz};$ $V_r = 0.5\text{ Vpp}$
Reset Generator						
Switching threshold	$V_{Q,\text{rt}}$	4.5	4.65	4.8	V	$V_{\text{RADJ}} = 0\text{ V}$
Reset adjust threshold	V_{RADJ}	1.26	1.35	1.44	V	$V_Q > 3.5\text{ V}$
Saturation voltage	V_{RO}	–	0.10	0.40	V	$I_{\text{RO}} = 1\text{ mA}$
Saturation voltage	$V_{\text{D,sat}}$	–	50	100	mV	$V_Q < V_{\text{RT}}$
Charge current	$I_{\text{D,c}}$	6	10	15	μA	–
Upper timing threshold	V_{DU}	1.4	1.8	2.2	V	–
Lower timing threshold	V_{DRL}	0.20	0.35	0.55	V	–
Reset delay time	t_{rd}	–	17	–	ms	$C_{\text{D}} = 100\text{ nF}$
Reset reaction time	t_{rr}	–	1.2	–	μs	$C_{\text{D}} = 100\text{ nF}$

Table 3 Characteristics (cont'd)

$V_1 = 13.5\text{ V}$; $T_j = 25\text{ °C}$; $V_{INH} > 3.5\text{ V}$; (unless specified otherwise)

Parameter	Symbol	Limit Values			Unit	Test Condition
		Min.	Typ.	Max.		
Inhibit						
Switch-ON voltage	$V_{INH,ON}$	3.6	–	–	V	IC turned on
Switch-OFF voltage	$V_{INH,OFF}$	–	–	0.8	V	IC turned off
Input current	I_{INH}	5	10	25	μA	$V_{INH} = 5\text{ V}$

1) Drop voltage $V_1 \geq 4.5\text{ V}$; drop voltage = $V_1 - V_Q$ (below regulating range)

Note: The reset output is low within the range $1\text{ V} \leq V_Q \leq V_{Q,rt}$.

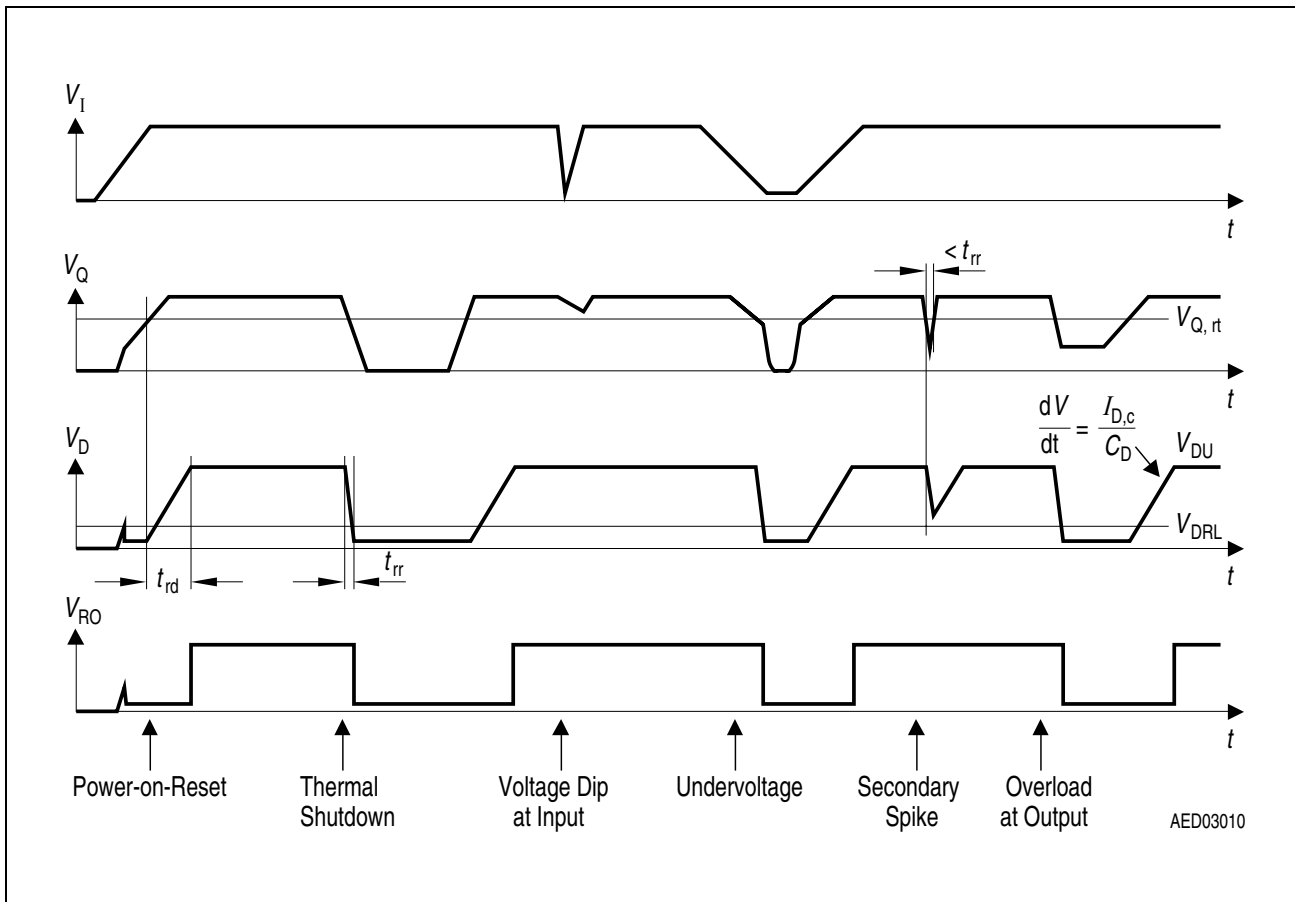


Figure 5 Time Response

Reset Timing

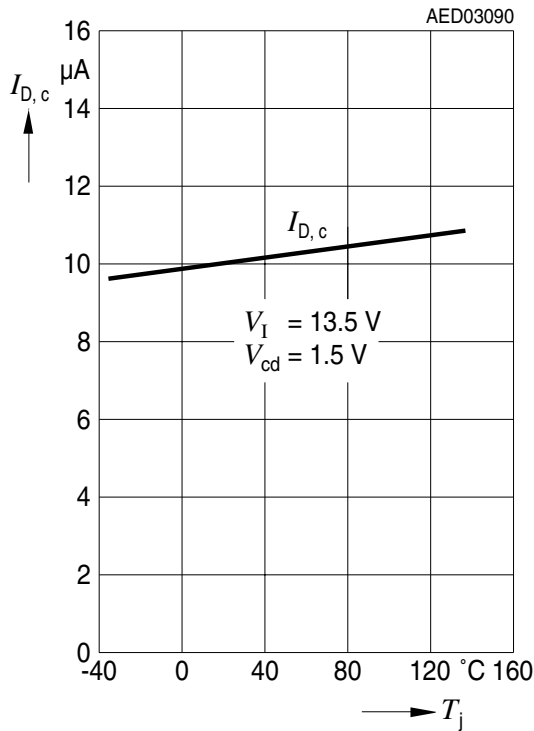
The power-on reset delay time is defined by the charging time of an external capacitor C_D which can be calculated as follows:

$$C_D = (\Delta t_{rd} \times I_{D,c}) / \Delta V \tag{1}$$

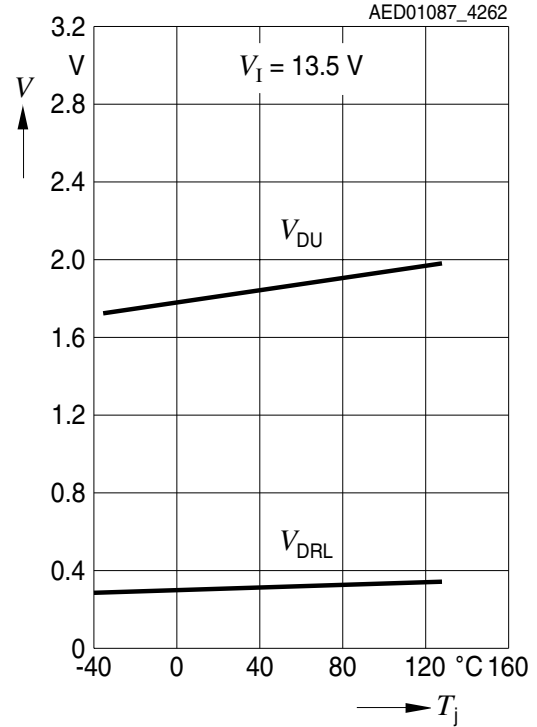
Definitions:

- C_D = delay capacitor
- Δt_{rd} = delay time
- $I_{D,c}$ = charge current, typical 10 μ A
- ΔV = V_{DU} , typical 1.8 V
- V_{DU} = upper delay switching threshold at C_D for reset delay time

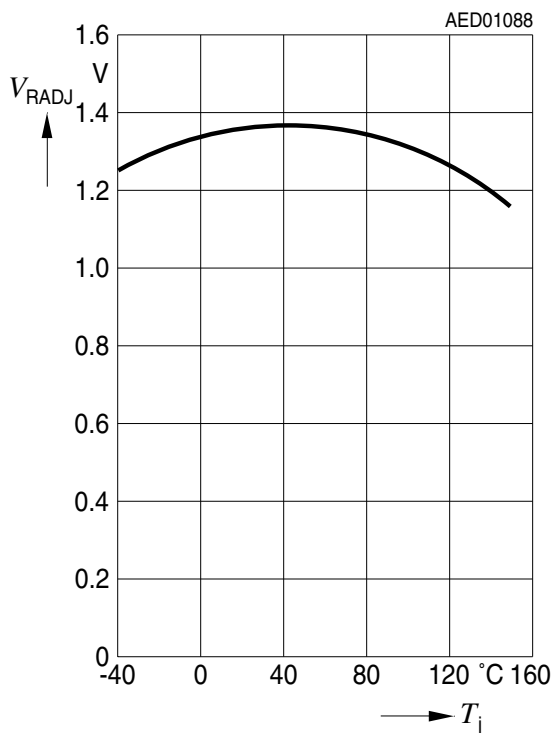
Charge Current versus Temperature



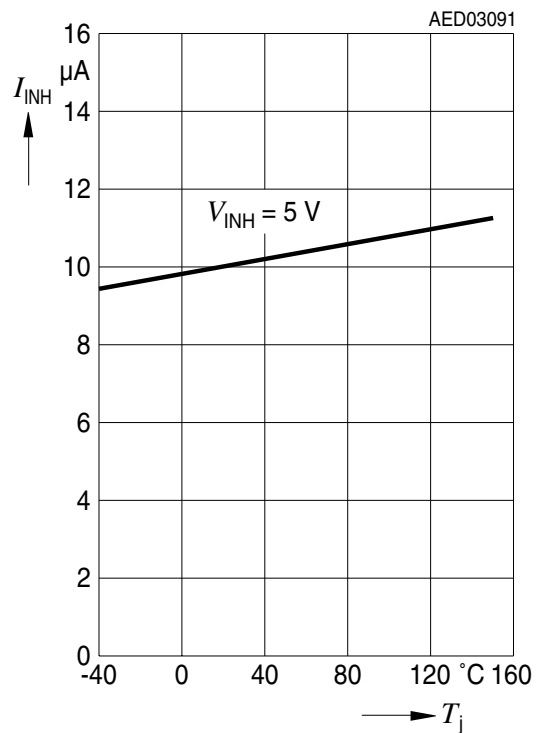
Upper and Lower Timing Threshold V_{DU} and V_{DRL} versus Temperature



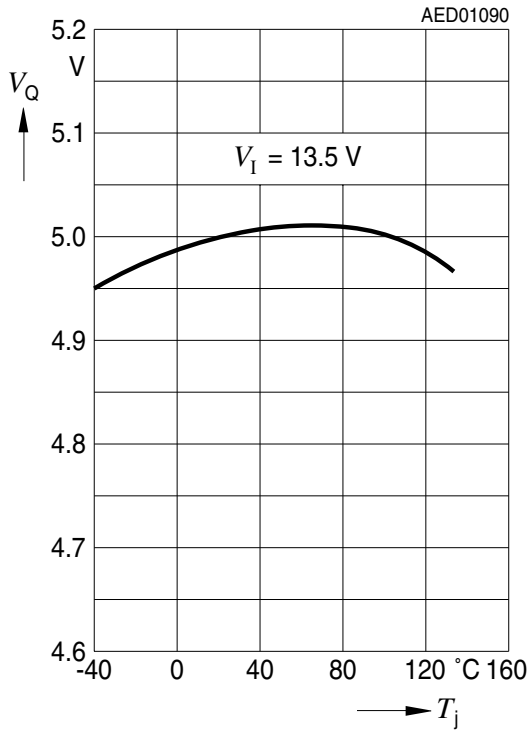
Reset Switching Threshold versus Temperature



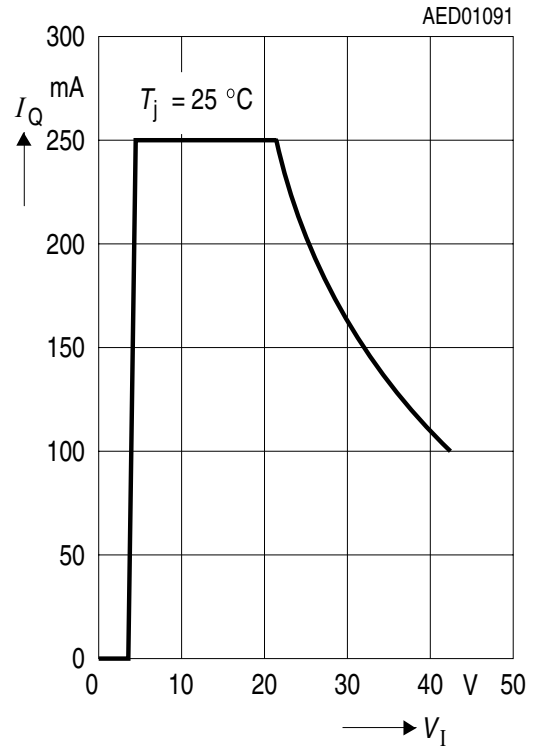
Current Consumption of Inhibit versus Temperature Output Current



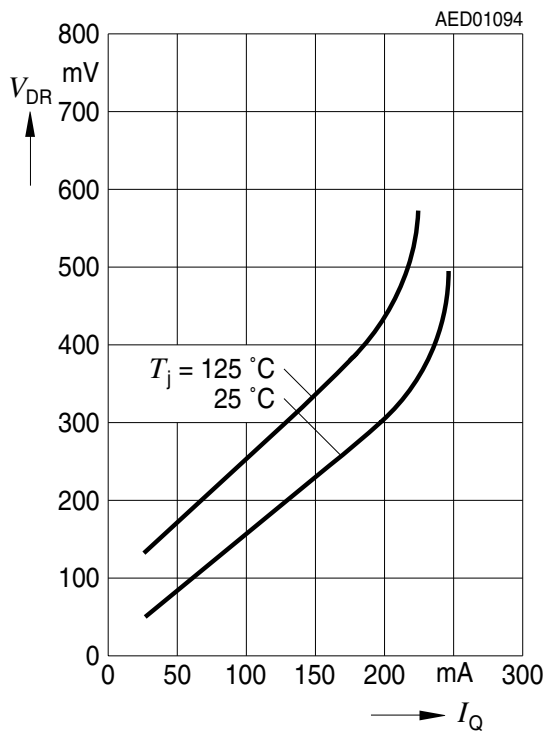
Output Voltage versus Temperature



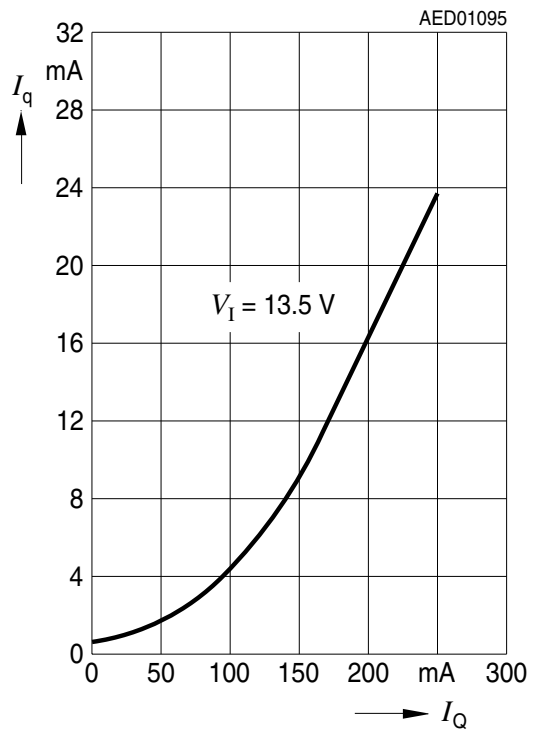
Output Current versus Input Voltage



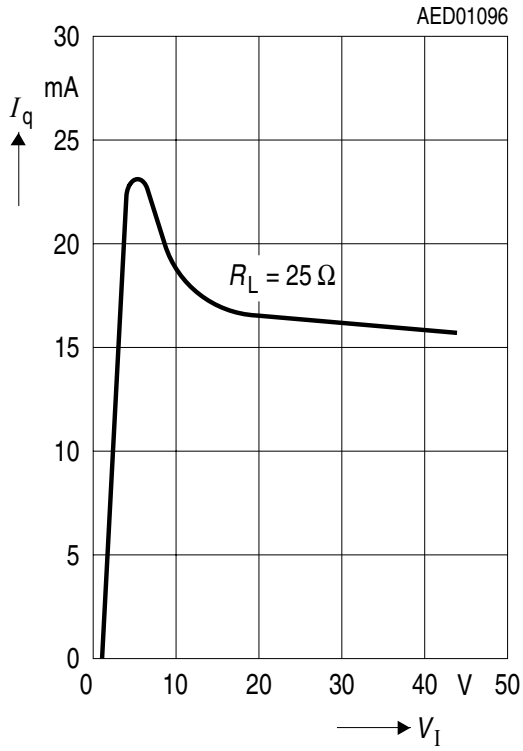
Drop Voltage versus Output Current



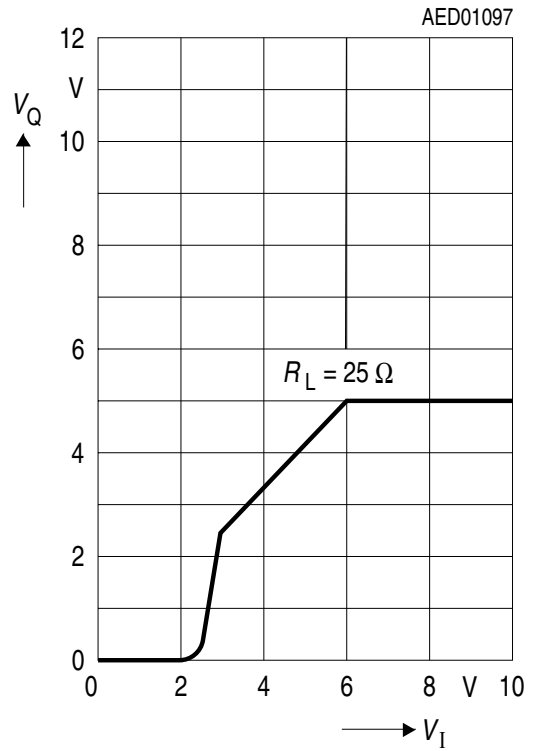
Current Consumption versus Output Current



Current Consumption versus Input Voltage



Output Voltage versus Input Voltage



Package Outlines

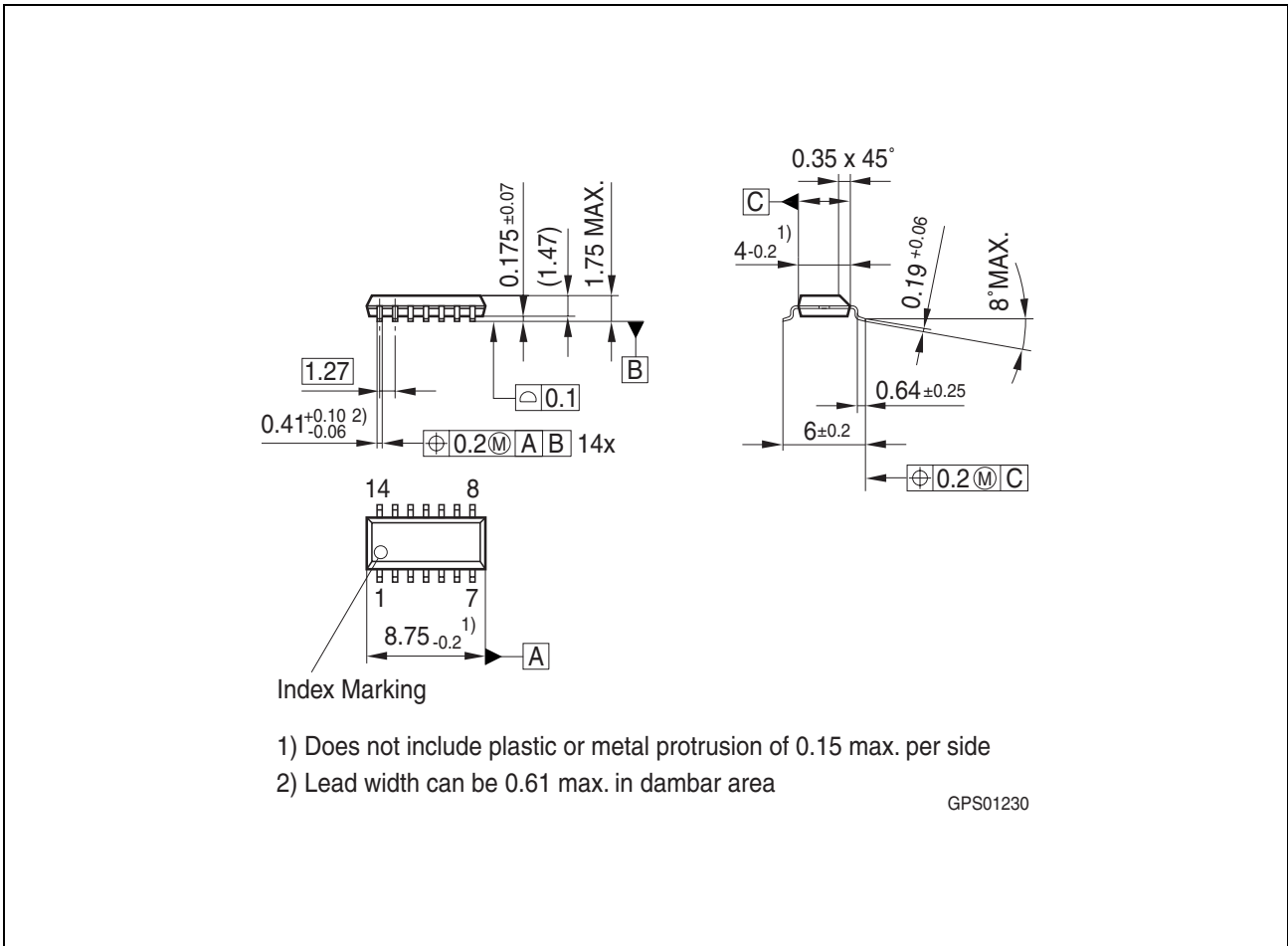


Figure 6 PG-DSO-14-30 (Plastic Dual Small Outline)

Green Product (RoHS compliant)

To meet the world-wide customer requirements for environmentally friendly products and to be compliant with government regulations the device is available as a green product. Green products are RoHS-Compliant (i.e Pb-free finish on leads and suitable for Pb-free soldering according to IPC/JEDEC J-STD-020).

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SMD = Surface Mounted Device

Dimensions in mm

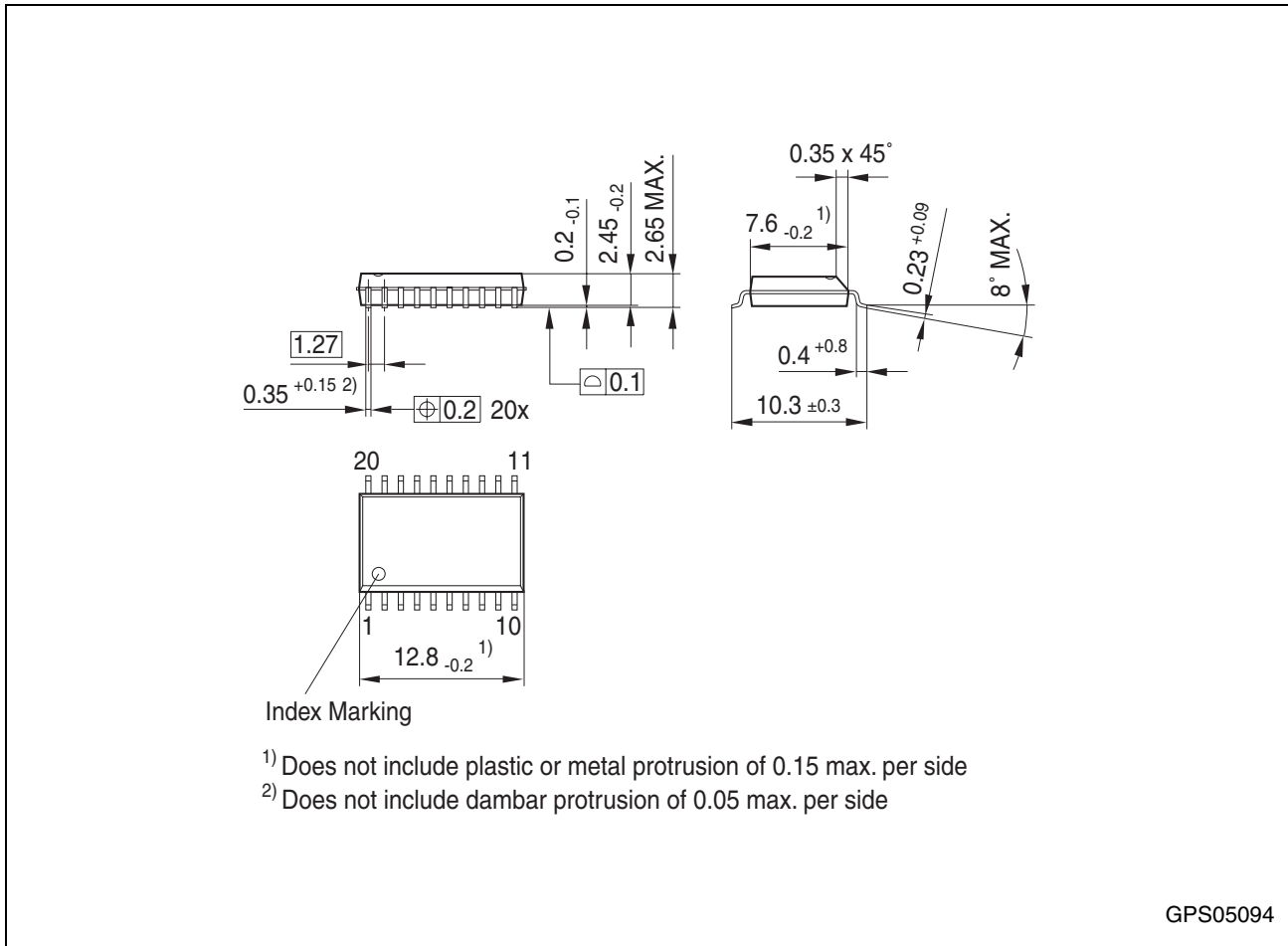


Figure 7 PG-DSO-20-35 (Plastic Dual Small Outline)

Green Product (RoHS compliant)

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SMD = Surface Mounted Device

Dimensions in mm

Revision History

Version	Date	Changes
Rev. 2.8	2008-05-19	Modification according to PCN No. 2008-096: Typo corrected: Current consumption I_q specification @ $I_Q = 150\text{mA}$ on page 6.
Rev. 2.7	2007-03-20	Initial version of RoHS-compliant derivate of TLE 4262 Page 1 : AEC certified statement added Page 1 and Page 13 ff: RoHS compliance statement and Green product feature added Page 1 and Page 13 ff: Package changed to RoHS compliant version Legal Disclaimer updated

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